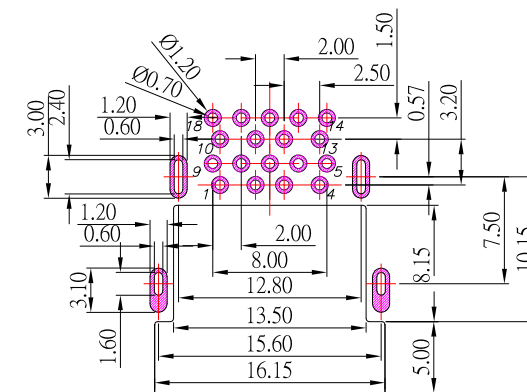
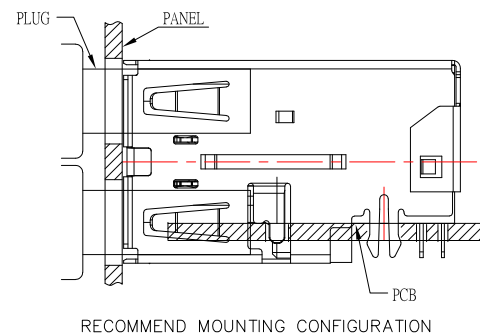
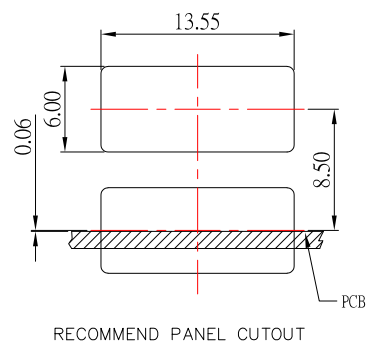
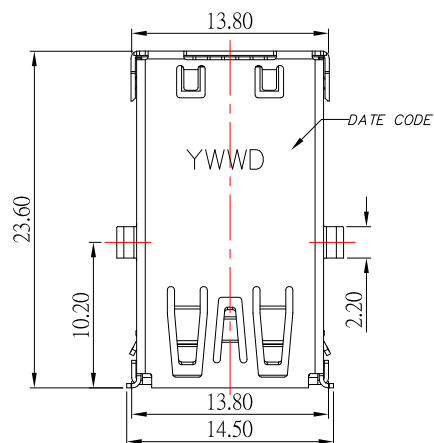
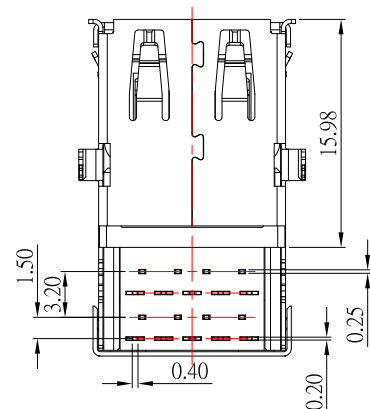
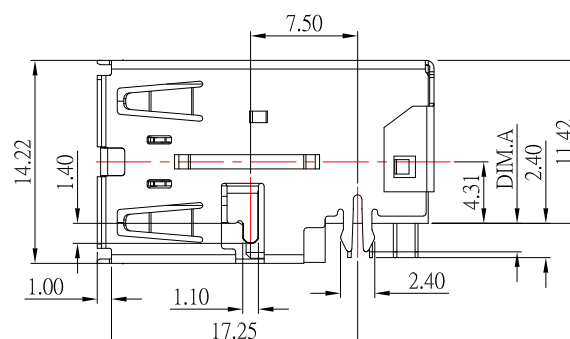
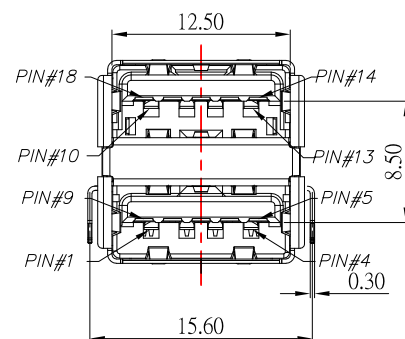




PCB LAYOUT TOP VIEW



SUA-210EHS2x30x-S410

DIM.A	
Blank	2.0mm
A	2.4mm

鍍層厚度 :	
Blank	1u"
2	15u"
3	30u"

NOTE:

1.MATERIAL:

- 1.1 Housing: PA4T,Blue
- 1.2 Cover: PA4T,Blue
- 1.3 Contact: 4PIN-Phosphor Bronze
5PIN-Brass

1.4 Shell: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Rating: 1.0A
- 3.2 Insulator Resistance:100MΩ Min
- 3.3 Dielectric Strength: 100V AC
- 3.4 Contact Resistance: 30mΩ Max

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY:	DATE	MAT'L		TITLE	CONNECTOR
Jack Lu	08/27/25	FINISH		MODLE	USB AF 3.0 雙層沉板 DIP 90 度 L23.60
CHECKED BY:	DATE	SCALE	1 : 1	DWG NO.	SUA-210EHS2x30x-S410
Jacky Chen	08/27/25	SHEET NO.	1 of 1	PART NO.	SUA-210EHS2x30x-S410
APPROVED BY:	DATE				
Tony Kao	08/27/25				

ITEM NO.	DESCRIPTION	DRAWN	DATE
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